



2815  
#6/A  
1/15/03  
Smith

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Harry Hedler et al.                      Art Unit : 2815  
Serial No. : 10/032,941                                  Examiner : Sheila Clark  
Filed : October 31, 2001  
Title : COMPLIANT RELIEF WAFER LEVEL PACKAGING

Commissioner for Patents,  
Washington, D.C. 20231

AMENDMENT

In response to the action mailed September 23, 2002, please amend the above identified application as follows:

IN THE CLAIMS:

Please amend claim 1, as follows:

A1  
1/15/03

-- 1. (Once Amended) A semiconductor structure, comprising:  
a semiconductor substrate; and  
a compliant <sup>electrical</sup> interconnect element disposed on a first surface of the substrate, said  
compliant interconnect element defining a chamber between the first surface of the  
substrate and the interconnect element.--

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CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

December 23, 2002

Date of Deposit

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Stefanie Dion

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